

AM26LS31 クワッド差動ラインドライバ

1 特長

- ANSI TIA/EIA-422-B と ITU の要件を満たす、または上回る性能
- 5V 単一電源で動作
- TTL 互換
- 相補出力
- 電源オフ状況での高い出力インピーダンス
- 相補出力のイネーブル入力
- MIL-PRF-38535 認定オプション (M) を利用可能:
特に記述のない限り、すべてのパラメータはテスト済みです。その他のすべての製品については、量産プロセスにすべてのパラメータのテストが含まれているとは限りません。

2 アプリケーション

- モータ エンコーダ
- フィールドトランスミッタ: 圧力センサおよび温度センサ
- 軍事 / 航空電子機器用の画像処理
- Modbus 使用の温度センサまたはコントローラ

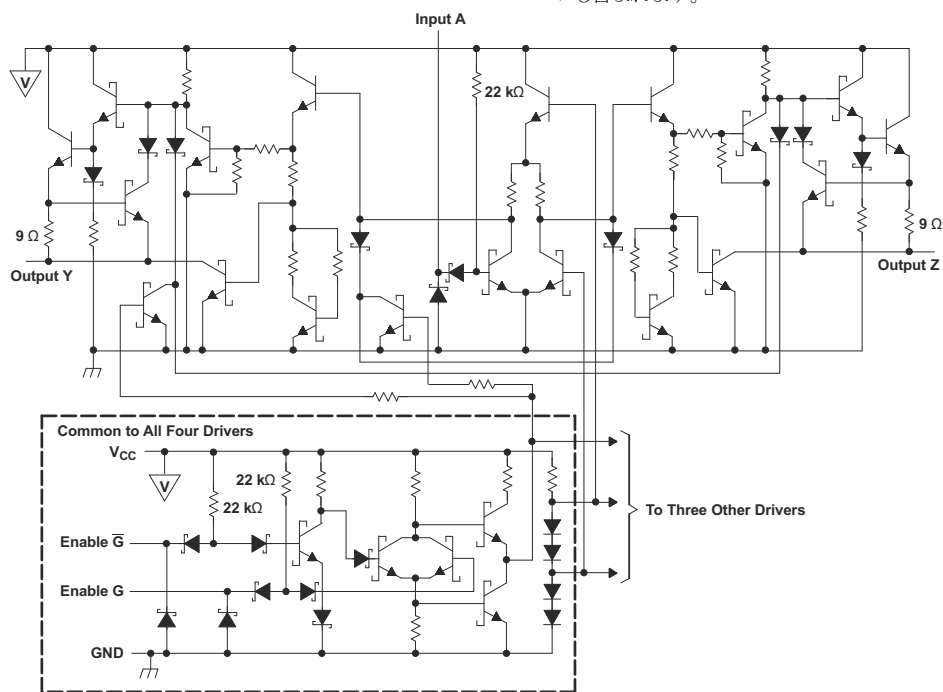
3 概要

AM26LS31CN-E ファミリのデバイスは、クワッド相補出力ラインドライバで、ANSI TIA/EIA-422-B および ITU (従来の CCITT) 勧告 V.11 の要件を満たすよう設計されています。3 ステート出力は、ツイストペアまたは平行線伝送線路などの平衡ラインを駆動するための大電流能力を備え、電源オフ時には高インピーダンス状態になります。イネーブル機能は 4 つのドライバすべてに共通で、アクティブ High またはアクティブ Low のイネーブル (G、 \bar{G}) 入力を選択できます。低消費電力のショットキー回路により、速度を犠牲にすることなく消費電力を削減しています。

パッケージ情報

部品番号	パッケージ (1)	パッケージ サイズ(2)
AM26LS31MFK	LCCC (20)	8.89mm × 8.89mm
AM26LS31MJ	CDIP (16)	19.6mm × 6.92mm
AM26LS31MW	CFP (16)	10.3mm × 6.73mm
AM26LS31CD	SOIC (16)	9.9mm × 3.91mm
AM26LS31CDB	SSOP (16)	6.2mm × 5.3mm
AM26LS31CN-E	PDIP (16)	19.3mm × 6.35mm
AM26LS31xNS	SO (16)	10.3mm × 5.3mm

- 詳細については、[セクション 11](#) を参照してください。
- パッケージ サイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。



All resistor values are nominal.

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回路図 (各ドライバ)



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4 Pin Configuration and Functions

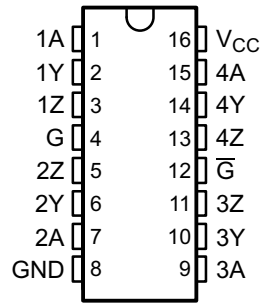


図 4-1. D (SOIC), DB (SSOP), N (PDIP), NS (SO), J (CDIP), or W (CFP) Packages
 (Top View)

表 4-1. Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
1A	1	I	Logic Data Input to RS422 Driver number 1
1Y	2	O	RS-422 Data Line (Driver 1)
1Z	3	O	RS-422 Data Line (Driver 1)
G	4	I	Driver Enable (active high)
\bar{G}	12	I	Driver Enable (active Low)
2A	7	I	Logic Data Input to RS422 Driver number 2
2Y	6	O	RS-422 Data Line (Driver 2)
2Z	5	O	RS-422 Data Line (Driver 2)
3A	9	I	Logic Data Input to RS422 Driver number 3
3Y	10	O	RS-422 Data Line (Driver 3)
3Z	11	O	RS-422 Data Line (Driver 3)
4A	15	I	Logic Data Input to RS422 Driver number 4
4Y	14	O	RS-422 Data Line (Driver 4)
4Z	13	O	RS-422 Data Line (Driver 4)
VCC	16	–	Power Input. Connect to 5V Power Source.
GND	8	–	Device Ground Pin

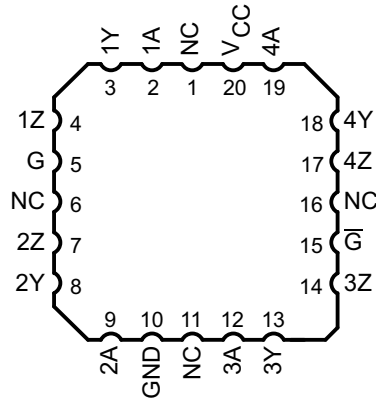


図 4-2. FK (LCCC) 20-Pin Package (Top View)

表 4-2. Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
1A	1	I	Logic Data Input to RS422 Driver number 1
1Y	2	O	RS-422 Data Line (Driver 1)
1Z	3	O	RS-422 Data Line (Driver 1)
G	4	I	Driver Enable (active high)
\bar{G}	12	I	Driver Enable (active Low)
2A	7	I	Logic Data Input to RS422 Driver number 2
2Y	6	O	RS-422 Data Line (Driver 2)
2Z	5	O	RS-422 Data Line (Driver 2)
3A	9	I	Logic Data Input to RS422 Driver number 3
3Y	10	O	RS-422 Data Line (Driver 3)
3Z	11	O	RS-422 Data Line (Driver 3)
4A	15	I	Logic Data Input to RS422 Driver number 4
4Y	14	O	RS-422 Data Line (Driver 4)
4Z	13	O	RS-422 Data Line (Driver 4)
VCC	8	I	Power Input. Connect to 5V Power Source.
GND	16	I	Device Ground Pin

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage ⁽²⁾		7	V
V _I	Input voltage		7	V
	Output off-state voltage		5.5	V
	Lead temperature 1,6 mm (1/16 in) from case for 10 s		260	°C
	Lead temperature 1,6 mm (1/16 in) from case for 60 s	J package	300	°C
T _{stg}	Storage temperature	-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential output voltage V_{OD}, are with respect to network GND.

5.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

		MIN	NOM	MAX	UNIT	
V _{CC}	Supply voltage	AM26LS31C	4.75	5	5.25	V
		AM26LS31M	4.5	5	5.5	
V _{IH}	High-level input voltage	2			V	
V _{IL}	Low-level input voltage			0.8	V	
I _{OH}	High-level output current			-20	mA	
I _{OL}	Low-level output current			20	mA	
T _A	Operating free-air temperature	AM26LS31C	0	70	°C	
		AM26LS31I	-40	85		
		AM26LS31M	-55	125		

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾	AM26LS31x				UNIT	
	D (SOIC)	DB (SSOP)	N (PDIP)	NS (SO)		
	16 PINS	16 PINS	16 PINS	16 PINS		
R _{θJA}	Junction-to-ambient thermal resistance ⁽²⁾	84.6	82	60.6	88.5	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	43.5	–	48.1	46.2	°C/W
R _{θJB}	Junction-to-board thermal resistance	43.2	–	40.6	50.7	°C/W
ψ _{JT}	Junction-to-top characterization parameter	10.4	–	27.5	13.5	°C/W
ψ _{JB}	Junction-to-board characterization parameter	42.8	–	40.3	50.3	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.
- (2) The package thermal impedance is calculated in accordance with JESD 51-7.

5.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V _{IK}	Input clamp voltage	V _{CC} = MIN, I _I = -18mA			-1.5	V
V _{OH}	High-level output voltage	V _{CC} = MIN, I _{OH} = -20mA	2.5			V
V _{OL}	Low-level output voltage	V _{CC} = MIN, I _{OL} = 20mA			0.5	V
I _{OZ}	Off-state (high-impedance-state) output current	V _{CC} = MIN,	V _O = 0.5V		-20	μA
			V _O = 2.5V		20	
I _I	Input current at maximum input voltage	V _{CC} = MAX, V _I = 7V			0.1	mA
I _{IH}	High-level input current	V _{CC} = MAX, V _I = 2.7V			20	μA
I _{IL}	Low-level input current	V _{CC} = MAX, V _I = 0.4V			-0.36	mA
I _{OS}	Short-circuit output current ⁽³⁾	V _{CC} = MAX	-30		-150	mA
I _{CC}	Supply current	V _{CC} = MAX, all outputs disabled		32	80	mA

(1) For C-suffix devices, V_{CC} min = 4.75V and V_{CC} max = 5.25V. For M-suffix devices, V_{CC} min = 4.5V and V_{CC} max = 5.5V.

(2) All typical values are at V_{CC} = 5V and T_A = 25°C.

(3) Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

5.6 Switching Characteristics – AM26LS31

T_A = 25°C, V_{CC} = 5V (see [6-1](#))

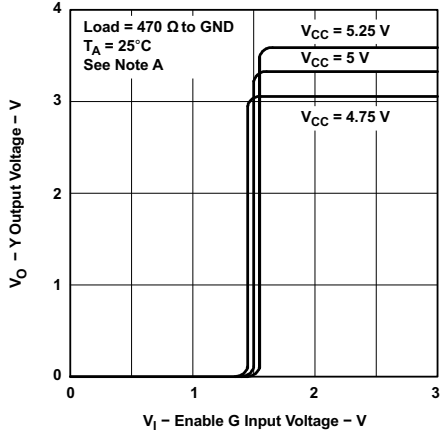
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	Propagation delay time, low- to high-level output	C _L = 30pF, S1 and S2 open		14	20	ns
t _{PHL}	Propagation delay time, high- to low-level output			14	20	
t _{PZH}	Output enable time to high level	C _L = 30pF	R _L = 75Ω		25	ns
t _{PZL}	Output enable time to low level		R _L = 180Ω		37	
t _{PHZ}	Output disable time from high level	C _L = 10pF, S1 and S2 closed		21	30	ns
t _{PLZ}	Output disable time from low level			23	35	
t _{SKEW}	Output-to-output skew	C _L = 30pF, S1 and S2 open		1	6	ns

5.7 Switching Characteristics – AM26LS31M

T_A = 25°C, V_{CC} = 5V (see [6-1](#))

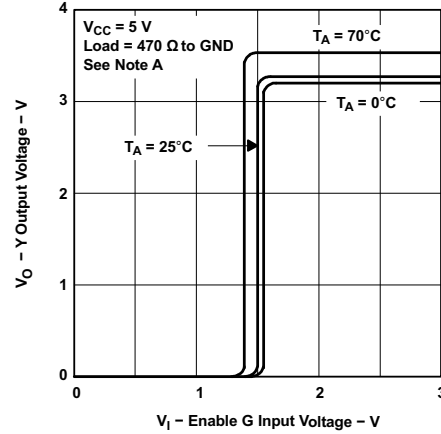
PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT	
t _{PLH}	Propagation delay time, low- to high-level output	C _L = 30pF, S1 and S2 open		30	ns	
t _{PHL}	Propagation delay time, high- to low-level output			30		
t _{PZH}	Output enable time to high level	C _L = 30pF	R _L = 75Ω		60	ns
t _{PZL}	Output enable time to low level		R _L = 180Ω		68	
t _{PHZ}	Output disable time from high level	C _L = 10pF, S1 and S2 closed		45	ns	
t _{PLZ}	Output disable time from low level			53		
t _{SKEW}	Output-to-output skew	C _L = 30pF, S1 and S2 open		9	ns	

5.8 Typical Characteristics



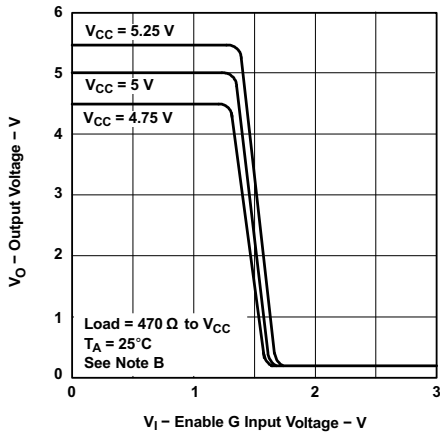
A. The A input is connected to V_{CC} during testing of the Y outputs and to ground during testing of the Z outputs.

图 5-1. Output Voltage vs Enable G Input Voltage



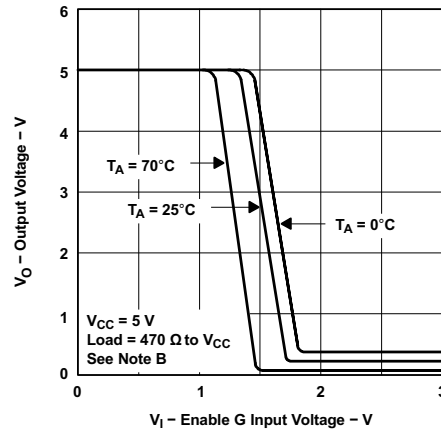
A. The A input is connected to V_{CC} during testing of the Y outputs and to ground during testing of the Z outputs.

图 5-2. Output Voltage vs Enable G Input Voltage



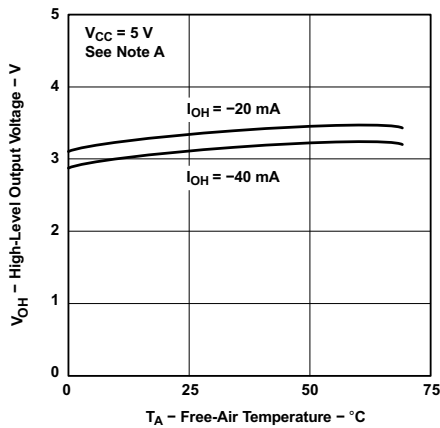
B. The A input is connected to ground during testing of the Y outputs and to V_{CC} during testing of the Z outputs.

图 5-3. Output Voltage vs Enable G Input Voltage



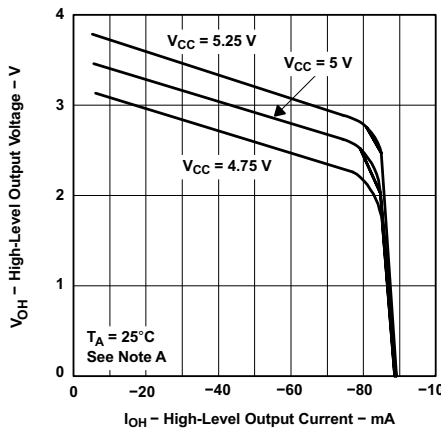
B. The A input is connected to ground during testing of the Y outputs and to V_{CC} during testing of the Z outputs.

图 5-4. Output Voltage vs Enable G Input Voltage



A. The A input is connected to V_{CC} during testing of the Y outputs and to ground during testing of the Z outputs.

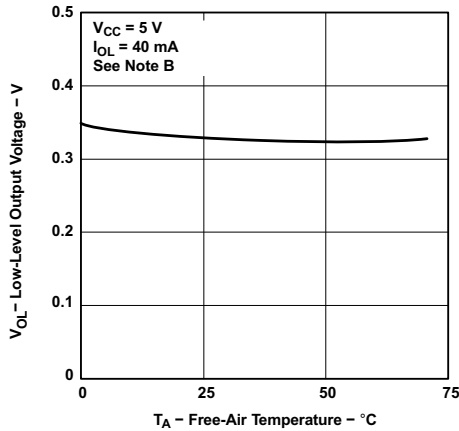
图 5-5. High-Level Output Voltage vs Free-Air Temperature



A. The A input is connected to V_{CC} during testing of the Y outputs and to ground during testing of the Z outputs.

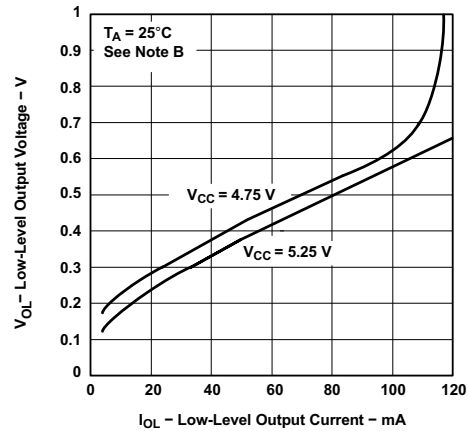
图 5-6. High-Level Output Voltage vs High-Level Output Current

5.8 Typical Characteristics (continued)



B. The A input is connected to ground during testing of the Y outputs and to V_{CC} during testing of the Z outputs.

图 5-7. Low-Level Output Voltage vs Free-Air Temperature



B. The A input is connected to ground during testing of the Y outputs and to V_{CC} during testing of the Z outputs.

图 5-8. Low-Level Output Voltage vs Low-Level Output Current

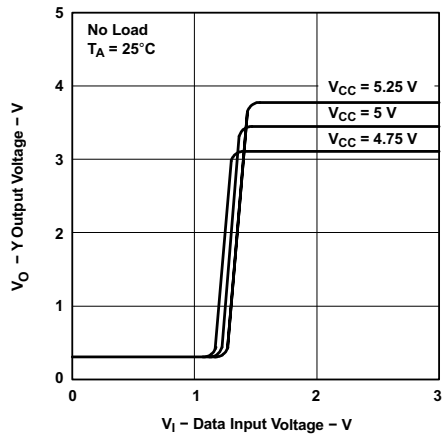


图 5-9. Y Output Voltage vs Data Input Voltage

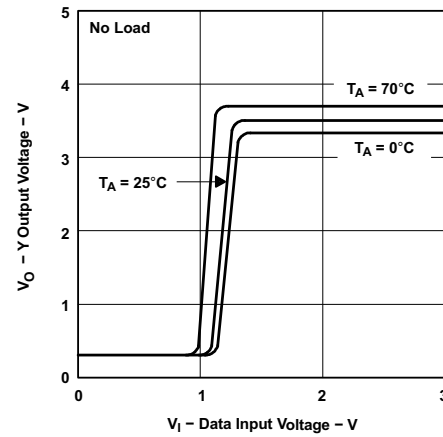
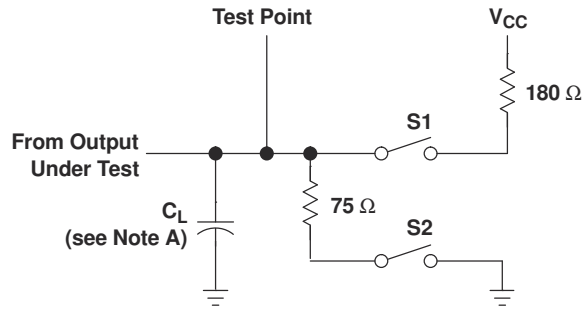
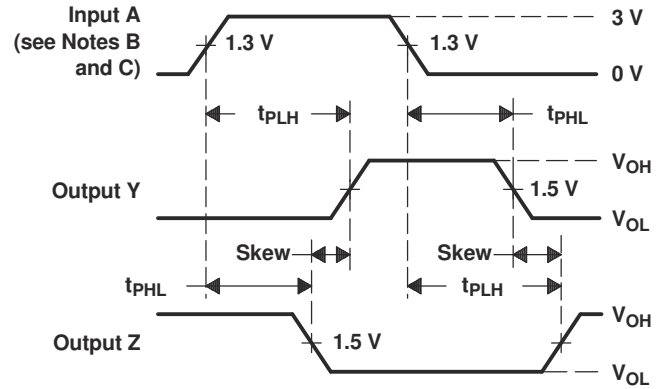


图 5-10. Y Output Voltage vs Data Input Voltage

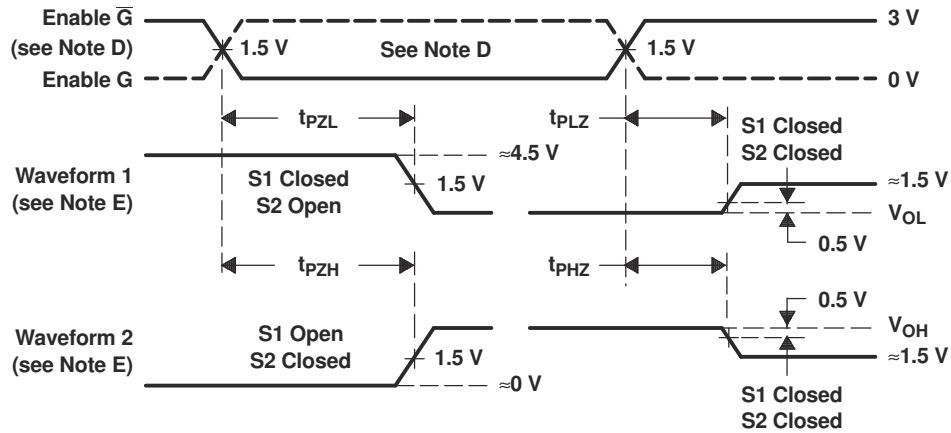
6 Parameter Measurement Information



PROPAGATION DELAY TIMES AND SKEW



TEST CIRCUIT



ENABLE AND DISABLE TIME WAVEFORMS

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O \approx 50 \Omega$, $t_r \leq 15$ ns, $t_f \leq 6$ ns.
 - C. When measuring propagation delay times and skew, switches S1 and S2 are open.
 - D. Each enable is tested separately.
 - E. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

6-1. Test Circuit and Voltage Waveforms

7 Detailed Description

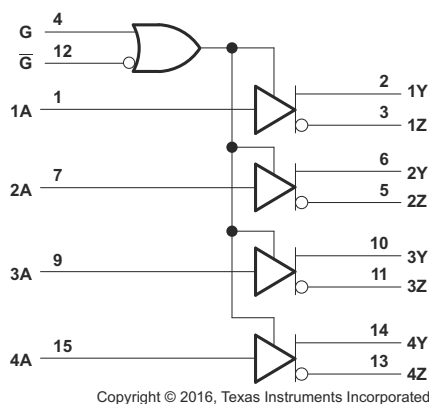
7.1 Overview

The AM26LS31x CN-E differential bus transmitter is a monolithic integrated circuit designed for unidirectional data communication on transmission lines. It is designed for balanced transmission lines and meets ANSI Standard EIA/TIA-422-B and ITU Recommendation V.11.

The AM26LS31x CN-E has a four 3-state differential line drivers that operate from a single 5V power supply. The driver also integrates active-high and active-low enables for precise device control.

The driver is designed to handle loads of a minimum of $\pm 30\text{mA}$ of sink or source current. The driver features positive- and negative-current limiting for protection from line fault conditions.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Complementary Output-Enable Inputs

The AM26LS31x can be configured using the G and \bar{G} logic inputs to control transmitter outputs. Setting either G to a logic HIGH or \bar{G} to a logic LOW enables the transmitter outputs. If G is set to logic LOW and \bar{G} is set to logic HIGH, the transmitter outputs are disabled. See [表 7-1](#) for a complete truth table.

7.3.2 High Output Impedance in Power-Off Conditions

When the AM26LS31x transmitter outputs are disabled using G and \bar{G} , the outputs are set to a high impedance state.

7.3.3 Complementary Outputs

The AM26LS31x is the driver half of a pair of devices, with the AM26LS32 being the complementary receiver. TI recommends using these devices together for optimal performance, but any RS-422 compliant receive must ensure proper RS-422 communication and logic level translation.

7.4 Device Functional Modes

表 7-1 lists the functional modes of the AM26LS31CN-E.

表 7-1. Function Table⁽¹⁾
(Each Driver)

INPUT A	ENABLES		OUTPUTS	
	G	\bar{G}	Y	Z
H	H	X	H	L
L	H	X	L	H
H	X	L	H	L
L	X	L	L	H
X	L	H	Z	Z

- (1) H = high level, L = low level,
X = irrelevant,
Z = high impedance (off)

8 Application and Implementation

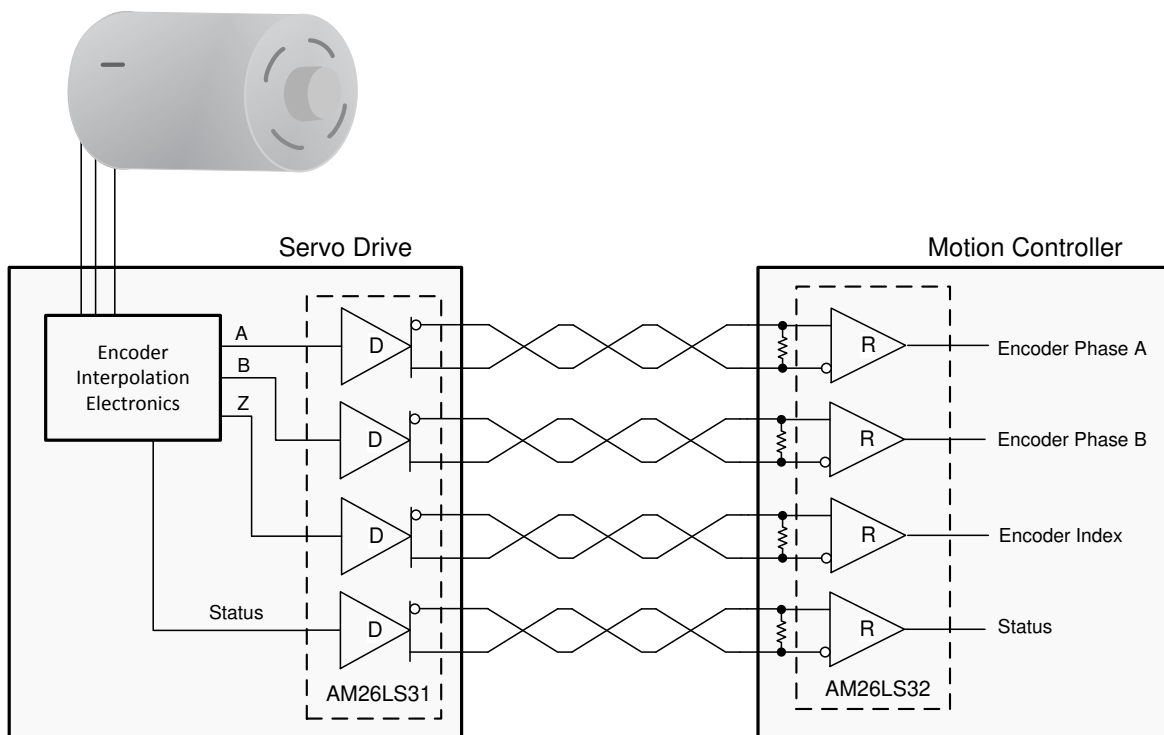
注

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8.1 Application Information

When designing a system that uses drivers, receivers, and transceivers that comply with RS-422 or RS-485, proper cable termination is essential for highly reliable applications with reduced reflections in the transmission line. Because RS-422 allows only one driver on the bus, if termination is used, it is placed only at the end of the cable near the last receiver. In general, RS-485 requires termination at both ends of the cable. Factors to consider when determining the type of termination usually are performance requirements of the application and the ever-present factor, cost. The different types of termination techniques discussed are unterminated lines, parallel termination, AC termination, and multipoint termination. Laboratory waveforms for each termination technique (except multipoint termination) illustrate the usefulness and robustness of RS-422 (and, indirectly, RS-485). Similar results can be obtained if 485-compliant devices and termination techniques are used. For laboratory experiments, 100 feet of 100Ω, 24-AWG, twisted-pair cable (Bertek) was used. A single driver and receiver, TI AM26LS31CN-E and AM26LS32C, respectively, were tested at room temperature with a 5V supply voltage. Two plots per termination technique are shown. In each plot, the top waveform is the driver input and the bottom waveform is the receiver output. To show voltage waveforms related to transmission-line reflections, the first plot shows output waveforms from the driver at the start of the cable; the second plot shows input waveforms to the receiver at the far end of the cable.

8.2 Typical Application



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図 8-1. Encoder Application

8.2.1 Design Requirements

This example requires the following:

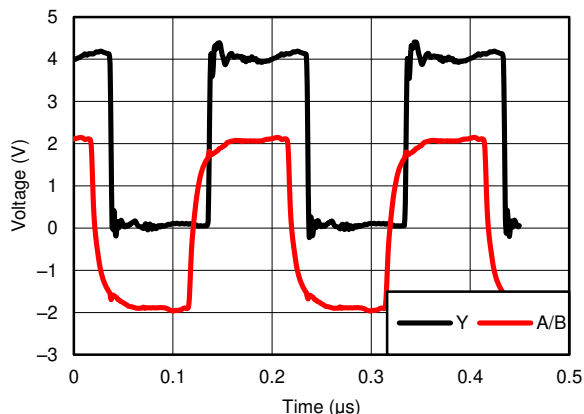
- 5V power source
- RS-485 bus operating at 10Mbps or less
- Connector that makes sure the correct polarity for port pins

8.2.2 Detailed Design Procedure

Place the device close to bus connector to keep traces (stub) short to prevent adding reflections to the bus line.

If desired, add external fail-safe biasing to ensure 200mV on the A-B port, if the drive is in high impedance state (see [Fail-safe in RS-485 data buses](#)).

8.2.3 Application Curve



8-2. Differential 120-Ω Terminated Output Waveforms (Cat 5E Cable)

8.3 Power Supply Recommendations

Place a 0.1μF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high impedance power supplies.

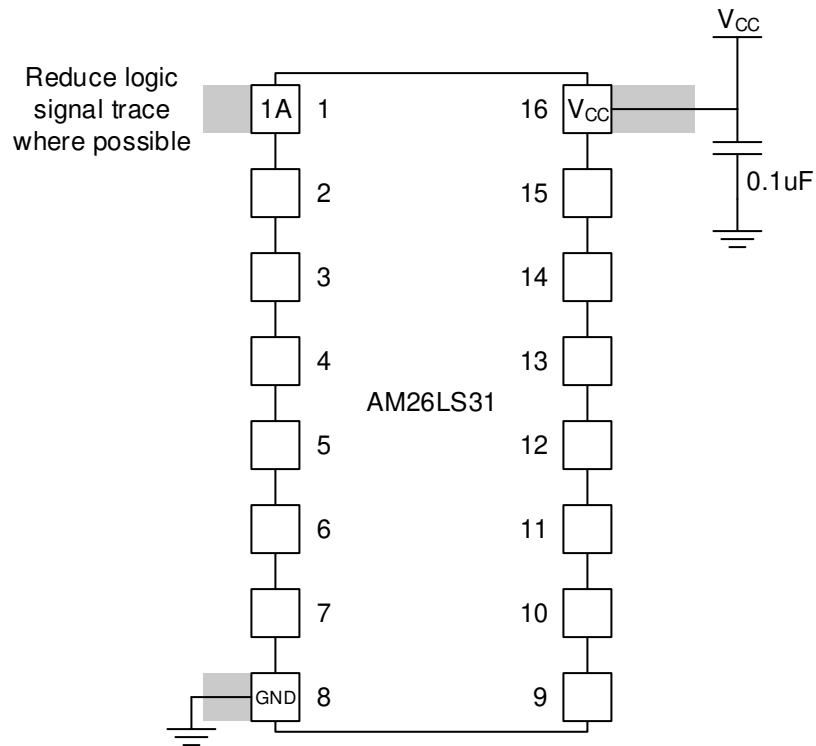
8.4 Layout

8.4.1 Layout Guidelines

For best operational performance of the device, use good PCB layout practices, including:

- Noise can often propagate into analog circuitry through the power supply of the circuit. Bypass capacitors are used to reduce the coupled noise by providing low impedance power sources local to the analog circuitry.
 - Connect low-ESR, 0.1μF ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for single-supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most-effective methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes. A ground plane helps distribute heat and reduces EMI noise pickup. Make sure to physically separate digital and analog grounds, paying attention to the flow of the ground current.
- To reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If it is not possible to keep them separate, it is much better to cross the sensitive trace perpendicular as opposed to in parallel with the noisy trace.
- Place the external components as close to the device as possible. Keeping RF and RG close to the inverting input minimizes parasitic capacitance.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.

8.4.2 Layout Example



8-3. Layout Recommendation

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Documentation

For related documentation, see the following:

[Failsafe in RS-485 data buses](#) (SLYT080)

9.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

9.3 サポート・リソース

テキサス・インスツルメンツ E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

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9.4 Trademarks

テキサス・インスツルメンツ E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

9.5 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

9.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision L (October 2018) to Revision M (March 2024)	Page
• 「製品情報」表を「パッケージ情報」表に変更.....	1
• Changed the <i>Thermal Information</i> table.....	5

Changes from Revision K (July 2016) to Revision L (October 2018)	Page
• Changed VCC pin number From: 8 To: 16 in the <i>Pin Functions</i> table	3
• Changed GND pin number From: 16 To: 8 in the <i>Pin Functions</i> table	3

Changes from Revision J (January 2014) to Revision K (February 2014)	Page
<ul style="list-style-type: none"> 「アプリケーション」セクション、「デバイス情報」表、「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加 1 Split up <i>Switching Characteristics</i> table into two tables specified for each part..... 6 	

Changes from Revision I (February 2006) to Revision J (January 2014)	Page
<ul style="list-style-type: none"> 新しい テキサス・インスツルメンツのデータシート フォーマットにドキュメントを更新 - 仕様変更なし。..... 1 「注文情報」表を削除。..... 1 「特長」を更新..... 1 	

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-7802301M2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7802301M2A AM26LS31 MFKB	Samples
5962-7802301MEA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7802301MEA AM26LS31MJB	Samples
5962-7802301MFA	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7802301MFA AM26LS31MWB	Samples
5962-7802301Q2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type		5962-7802301Q2A AM26LS31M	Samples
AM26LS31CD	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70	AM26LS31C	
AM26LS31CDBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	SA31C	Samples
AM26LS31CDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AM26LS31C	Samples
AM26LS31CDRG4	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70	AM26LS31C	
AM26LS31CN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	AM26LS31CN	Samples
AM26LS31CNSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	26LS31	Samples
AM26LS31INSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	26LS31	Samples
AM26LS31MFKB	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7802301M2A AM26LS31 MFKB	Samples
AM26LS31MJB	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7802301MEA AM26LS31MJB	Samples
AM26LS31MWB	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7802301MFA AM26LS31MWB	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of ≤ 1000 ppm threshold. Antimony trioxide based flame retardants must also meet the ≤ 1000 ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF AM26LS31, AM26LS31M :

● Catalog : [AM26LS31](#)

● Military : [AM26LS31M](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
AM26LS31CDBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
AM26LS31CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26LS31CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26LS31CNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
AM26LS31CNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
AM26LS31INSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
AM26LS31CDBR	SSOP	DB	16	2000	356.0	356.0	35.0
AM26LS31CDR	SOIC	D	16	2500	340.5	336.1	32.0
AM26LS31CDR	SOIC	D	16	2500	353.0	353.0	32.0
AM26LS31CNSR	SO	NS	16	2000	353.0	353.0	32.0
AM26LS31CNSR	SO	NS	16	2000	367.0	367.0	38.0
AM26LS31INSR	SO	NS	16	2000	356.0	356.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-7802301M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-7802301MFA	W	CFP	16	25	506.98	26.16	6220	NA
5962-7802301Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
AM26LS31CN	N	PDIP	16	25	506	13.97	11230	4.32
AM26LS31MFKB	FK	LCCC	20	55	506.98	12.06	2030	NA
AM26LS31MWB	W	CFP	16	25	506.98	26.16	6220	NA



PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES:

- All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

DB0016A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4220763/A 05/2022

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220763/A 05/2022

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16

GENERIC PACKAGE VIEW

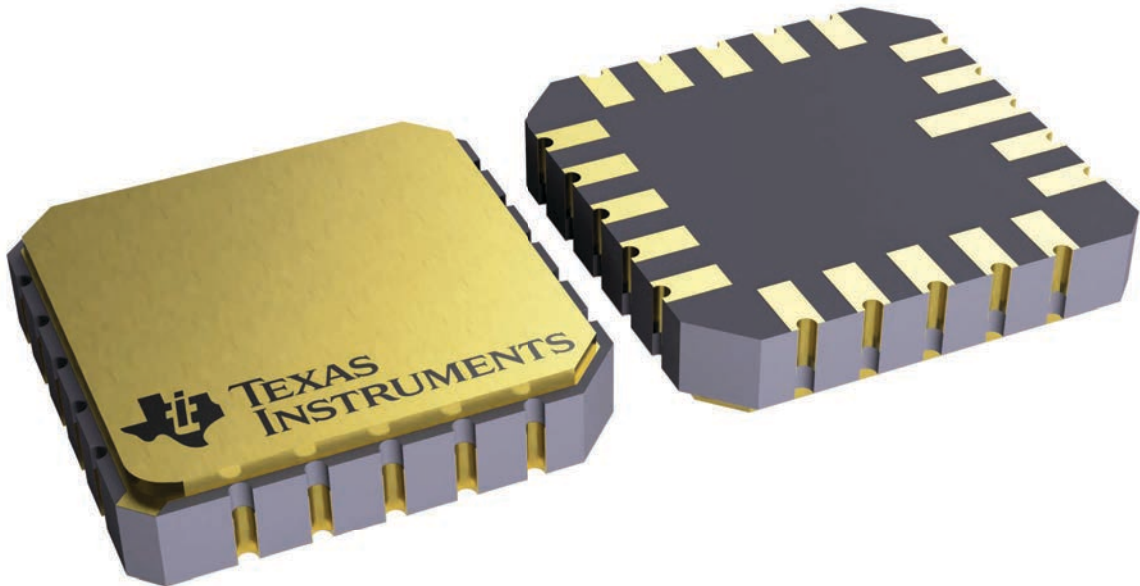
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4229370VA\

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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